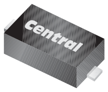
CMOD3003

SURFACE MOUNT
LOW LEAKAGE
SILICON SWITCHING DIODE

ULTRAmini™



SOD-523 CASE

www.centralsemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMOD3003 type is a silicon switching diode manufactured by the epitaxial planar process, epoxy molded in a ULTRAmini™ surface mount package, designed for switching applications requiring a extremely low leakage diode.

MARKING CODE: 3C

MAXIMUM RATINGS: (T_A=25°C)	**SYMBOL**		**UNITS**
Continuous Reverse Voltage	V_R	180	V
Average Rectified Current	I_O	200	mA
Continuous Forward Current	I_F	600	mA
Peak Repetitive Forward Current	I_{FRM}	700	mA
Peak Forward Surge Current, tp=1.0μs	I_{FSM}	2.0	A
Peak Forward Surge Current, tp=1.0s	I_{FSM}	1.0	A
Power Dissipation	P_D	250	mW
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	500	°C/W

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

SYMBOL	**TEST CONDITIONS**	**MIN**	**MAX**	**UNITS**
I_R	V_R=125V		1.0	nA
I_R	V_R=125V, T_A=150°C		3.0	μA
I_R	V_R=180V		10	nA
I_R	V_R=180V, T_A=150°C		5.0	μA
BV_R	I_R=5.0μA	200		V
V_F	I_F=1.0mA	0.62	0.72	V
V_F	I_F=10mA	0.72	0.83	V
V_F	I_F=50mA	0.80	0.89	V
V_F	I_F=100mA	0.83	0.93	V
V_F	I_F=200mA	0.87	1.10	V
V_F	I_F=300mA	0.90	1.15	V
C_T	V_R=0, f=1.0MHz		4.0	pF

R3 (11-April 2011)

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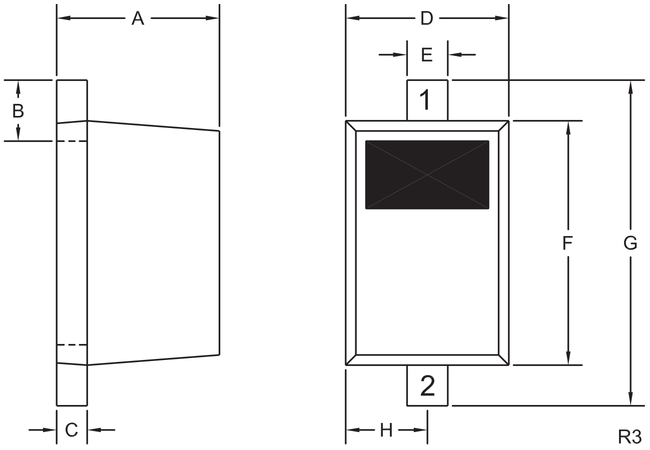
Central Semiconductor Corp.

SOD-523 CASE - MECHANICAL OUTLINE



LEAD CODE:
1) Cathode
2) Anode

MARKING CODE: 3C

DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.020	0.031	0.50	0.80
B	0.008	0.016	0.20	0.40
C	0.002	0.008	0.05	0.20
D	0.028	0.035	0.70	0.90
E	0.008	0.014	0.20	0.35
F	0.039	0.055	1.00	1.40
G	0.055	0.071	1.40	1.80
H	0.016		0.40	

SOD-523 (REV: R3)

R3 (11-April 2011)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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